ISPSD 2021
The 33rd International Symposium on Power Semiconductor Devices and ICs (ISPSD)
May 30 – June 3, 2021, NAGOYA, Japan

ISPSD is the premier forum for technical discussion in all areas of power semiconductor devices and integrated circuits, their hybrid technologies and applications. ISPSD 2021 will be held in the city Nagoya, known for samurai culture and industrial technology, and geographically located in the center of Japan.

<table>
<thead>
<tr>
<th>Main categories of interest include</th>
</tr>
</thead>
<tbody>
<tr>
<td>High Voltage Power Devices</td>
</tr>
<tr>
<td>Medium and high voltage Si bipolar devices such as IGBT, thyristor, pn diode, etc</td>
</tr>
<tr>
<td>Low Voltage Power Devices</td>
</tr>
<tr>
<td>Low and medium voltage Si unipolar devices such as power MOSFETs, SJ type devices, etc</td>
</tr>
<tr>
<td>New Material Power Devices</td>
</tr>
<tr>
<td>Power devices based on compound or new materials such as SiC, GaN, Ga2O3, and diamond</td>
</tr>
<tr>
<td>Power ICs</td>
</tr>
<tr>
<td>Integrated power devices and circuitry on a single or multi chip(s) architecture</td>
</tr>
<tr>
<td>Module and Package Technologies</td>
</tr>
<tr>
<td>Integrated power modules and packaging technologies (functionality, power density, isolation, reliability, device cooling, temperature endurance, manufacturing, materials, etc)</td>
</tr>
</tbody>
</table>

Important date

Abstract submission deadline is December 7, 2020
https://ispsd2021.com

Conference venue
Nagoya Congress Center
1-1 Atsuta-nishimachi, Atsuta-ku, Nagoya 466-0036

Access to Nagoya

Osaka
50min.

Kyoto
30min.

NAGOYA
100min.

Tokyo
30min.

Sapporo
50min.

Kansai International Airport (KIX)
35min.

Chubu Centrair International Airport (NGO)
30min.

Express train
Directly from the airport to Nagoya station by express train in 30 min.

Bus
Bus system from the airport to major hotels or downtown of Nagoya.

General Chair: Dr. Kimimori Hamada, PDPlus LLC.
Technical Program Chair: Prof. Ichiro Omura, Kyushu Institute of Technology.

Sponsored by

Technically co-Sponsored by